

FOR : BE SEMICONDUCTOR INDUSTRIES N.V.  
Ratio 6  
6921 RW Duiven  
The Netherlands

## **PRESS RELEASE**

### **BE Semiconductor Industries Announces 2009 Fourth Quarter and Annual Results Release and Conference Call and Webcast Date**

Duiven, the Netherlands, February 18, 2010, BE Semiconductor Industries N.V. ("Besicon") (Euronext: BESI), a leading manufacturer of assembly equipment for the semiconductor industry, will release results for the fourth quarter and year ended December 31, 2009, on Thursday, February 25, 2010 at 8.00 a.m. Continental European Time (2.00 a.m. New York time).

Besicon will host a conference call and audio webcast (log on via [www.besi.com](http://www.besi.com)) to discuss its results for the fourth quarter and year ended December 31, 2009, on Thursday, February 25, 2010 at 4.00 p.m. CET (10.00 a.m. New York time). The teleconference dial-in number is (31) 10 29 44 228. The audio webcast will remain available on [www.besi.com](http://www.besi.com).

#### **About BE Semiconductor Industries N.V.**

BE Semiconductor Industries N.V. designs, develops, manufactures, markets and services die sorting, flip chip and multi-chip die bonding, wire bonding, packaging and plating equipment for the semiconductor industry's assembly operations. Its customers consist primarily of leading U.S., European, Asian, Korean and Japanese semiconductor manufacturers and subcontractors which utilize its products for both array connect and conventional leadframe manufacturing processes.

#### **Contacts:**

Richard W. Blickman  
President & CEO  
Tel. (31) 26 319 4500  
[investor.relations@besi.com](mailto:investor.relations@besi.com)

Jan Willem Ruineman  
Chief Financial Officer  
Tel. (31) 26 319 4500  
[investor.relations@besi.com](mailto:investor.relations@besi.com)

#### **IR Contact Europe:**

Uneke Dekkers/Frank Jansen  
Citigate First Financial  
Tel. (31) 20 575 4021/24